

Title (en)

METHOD AND SYSTEM FOR ELECTROPLATING ARTICLE WITH METAL

Title (de)

VERFAHREN UND SYSTEM ZUR ELEKTROPLATTIERUNG EINES ARTIKELS MIT METALL

Title (fr)

PROCÉDÉ ET SYSTÈME DE PLACAGE ÉLECTROLYTIQUE D'UN ARTICLE AVEC UN MÉTAL

Publication

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Application

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Abstract (en)

The object of the present invention is to provide a method and system for electroplating without requiring ancillary facilities or anolyte control, while using an anode which can be relatively easily produced without requiring an expensive metal or special metal. When electroplating an article with metal, decomposition of an organic compound additive in a plating bath can be suppressed by using, as an anode, a conductive substrate having a layer comprising oxide or nitride of nickel and iron formed on a surface thereof.

IPC 8 full level

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